



Research and Application Progress of Wood Adhesives

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Message from the Guest Editors

In recent years, a continuous growth can be observed in the frame of adhesives and resins for the woodworking industry. Investigations concerning environmentally friendly products have been carried out, and proecological adhesives have been used for gluing not only wood but also composites and modified wood.

Adhesives or resins that are used for gluing have not always shown high thermoresistance and/or water resistance of glue lines, e.g., by gluing modified wood. The bonding characteristic of modified wood becomes a complex issue due to the large diversity of wood species, adhesives, and modification methods. The drying time of the binder increases a few times compared to unmodified wood. Sometimes, problems occur with gluability, and surface should be activated using different methods or tools, e.g., plasma treatment or adhesion promoters.

This Special Issue will serve as a forum for exchanging novel research ideas and application progress in the different groups of wood adhesives. Emphasis in this Special Issue is placed on the properties of adhesives, gluability of modified or activated wood and wood-based composites, and the strength and durability of glue lines.





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Message from the Editor-in-Chief

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